

INDUSTRY

Semiconductor

Particle, molecular contamination and electrostatic discharge control in semiconductor manufacturing.



DATASHEET PER PART NUMBER



STANDARDS REFERENCED



RECURRING CONSUMPTION

In a fab, the defect that kills a chip is a fraction of the geometry being printed. That is why contamination control in semiconductor work resembles no other industry: clean air is not enough, you also have to control what comes off surfaces, gloves and the very wiper used to clean.

PRODUCTS FOR THIS INDUSTRY



VANTERIS Polyester Wipe 9 × 9 in
VTN-WP-PES-LS-99
9 × 9 in (228.6 × 228.6 mm)



VANTERIS Sticky Mat 24 × 36 in, Blue
VTN-MAT-PE-STK-2436-BLU
24 × 36 in



VANTERIS Nonwoven Hood 40 × 42 cm, White
VTN-AP-PP-NH-UNI-WHT
40 × 42 cm



VANTERIS Foam Swab Large Round Head
VTN-SW-PU-LC-132
132.2 mm

TYPICAL CHALLENGES

- Particles below process geometry
- Molecular contamination in photolithography
- Electrostatic discharge on wafer and device
- Consumable compatibility with process solvents

REFERENCE STANDARDS

ISO 14644-1

Classifies air cleanliness by particle concentration (ISO Class 1 to 9).

ISO 14644-9

Classifies surface cleanliness by particle concentration.

IEST-RP-CC004

Method for evaluating cleanroom wiping materials.

ANSI/ESD S20.20

Requirements for an electrostatic discharge control programme.

VANTERIS

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Technical article and catalog

